

Thermally Conductive Adhesives

Elecolit®	6601	6603	6604			6616	6207
Typical Applications	Heat Sinks, Sensors	Bonding Magnets and Heat Sinks	Sensors for Measuring Instruments			Sealant for Curing at Room Temperature	Capsule and Sealant
Base	1-part Epoxy	1-part Epoxy	1-part Epoxy			2-part Epoxy	2-part Epoxy
Viscosity (mPas)	12,000 – 20,000	95,000 – 115,000	110,000 – 140,000			Pasty	9,000 – 12,000
Curing	20 min at 150 °C	20 min at 150 °C	10 min at 150 °C			2 h at 80 °C	2 h at 65 °C
Temp. Resist. (°C)	-40 to +200	-40 to +200	-40 to +200			-50 to +150	-55 to +110
Heat Conductivity (W/mK)	1.05	1.3	1.05			1.01	0.9
Special Properties	Very Good Adhesion to Metals, Excellent Flow Behaviour, High Strength, Good Dispensability	Slightly Flexible, Impact- and Temperature-Resistant, High Viscosity	Low Heat Expansion, No Influence on Transmitted Signals, High Viscosity			Pot Life 45 min, Flexible at Low Temperatures, Vibration- and Impact-Resistant, Visco-Plastic	Low Viscosity, Flame-Retardant, Low Shrinkage, Pot Life 2 hours, UL 94 V0